Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

- 1-8. (Cancelled)
- (Currently Amended) A semiconductor device comprising:

 a substrate having a regionregions irradiated with radiating rays,
 crystal defects within the regionregions irradiated,

impurity regions formed in the substrate, and

a metal wiring layer located over the entire substrate except at [[an]]

openingopenings above the regionregions irradiated, wherein radiating rays passing to the regionregions irradiated through the openingopenings generate the crystal defects under the openingopenings and so that a smaller amount of radiating rays are irradiated to regions elsewhere in said substrate as compared with said regionregions under the openingopenings, the metal wiring layer being connected to each of the impurity regions, the metal wiring layer being made of a light metal.

- 10. (Currently Amended) The semiconductor device in accordance with Claim 9, wherein the metal wiring layer is formed in a thickness so the smaller amount of radiating rays are irradiated to the regions elsewhere in said substrate except the region under the opening openings.
- 11. (Currently Amended) The semiconductor device in accordance with Claim 10, wherein an insulating layer is formed above the <u>regionregions</u> irradiated, the <u>openingopenings</u> being on the insulating layer.
- 12. (Previously Presented) The semiconductor device in accordance with Claim 11, wherein the metal wiring layer covers a part of the insulating layer.
- 13. (Currently Amended) The semiconductor device in accordance with Claim 12, wherein the semiconductor device is an insulated gate bipolar transistor, wherein <u>one of</u> the impurity

regionregions is a source region, and wherein one of the regionregions irradiated is a positive-negative junction where a parasitic diode is generated.

14. (Currently Amended) The semiconductor device in accordance with Claim 12, wherein the semiconductor device is a metal oxide semiconductor field effect transistor, wherein <u>one of</u> the impurity <u>regionregions</u> is a source region, and wherein <u>one of</u> the <u>regionregions</u> irradiated is a positive-negative junction region where a parasitic diode is generated.